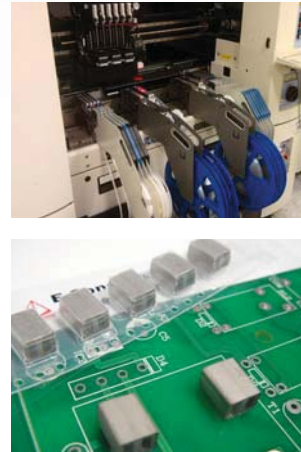
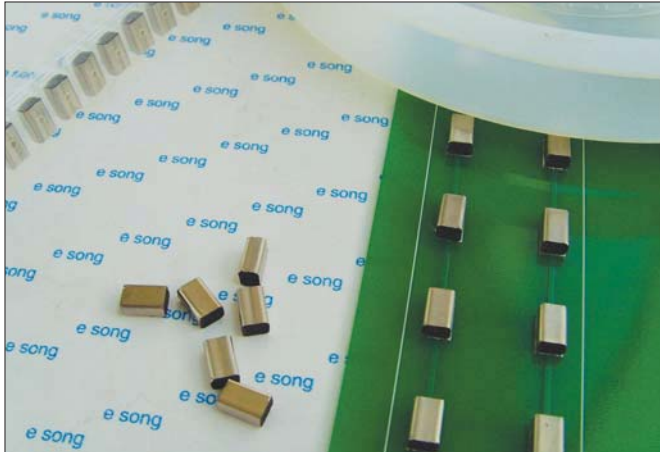


# SMD GROUNDING FOAM GASKET



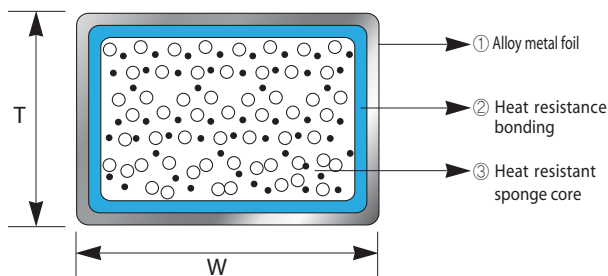
- [RoHS compliant](#)
- [Hologen Free](#)
- [SMD: Surface Mount Device](#)
- [Low surface resistance](#)
- [Reflow processable](#)

Smooth surface of alloy metal foil allows easy placement by pick-n-place equipment onto the PCB for further reflow tunnel processing.

## CHARACTERISTICS

- Superior thermal resistance
- Excellent electrical conductivity
- Suitable for high volume production using automated pick-n-place equipment
- Flame Retardant: UL94V0 (Certification pending)
- Economically priced

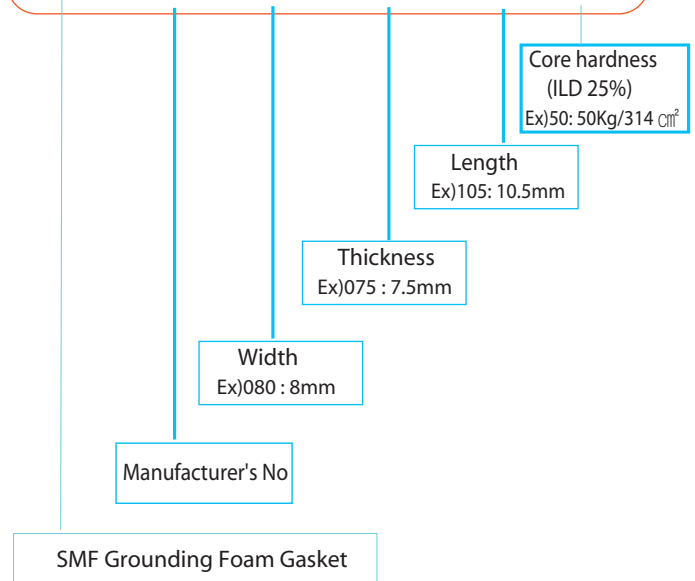
## STRUCTURE & MATERIAL



- ① Alloy metal foil: Ni alloy (Ex. T0.08mm)
- ② Heat resistant bonding: Silicone bond
- ③ Heat resistant sponge core: Silicone foam

## PART NUMBER STRUCTURE

**SMF-X X -X X X -X X X -X X X -X**

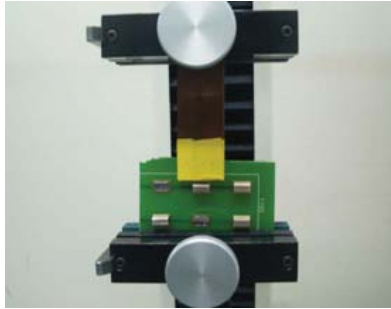


## SPECIFICATIONS

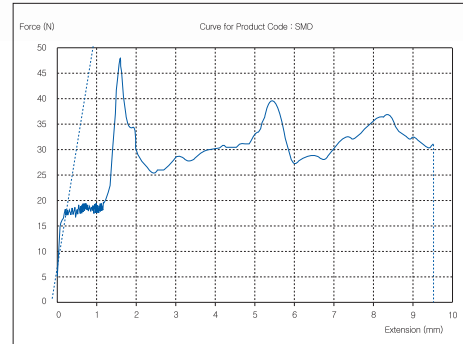
▶ Test sample size: 5(W) x 4(T) x 8(L) mm

Property		Unit	Value	Test Method	
Through-Thickness Resistance	Before Reflow	Ω	< 0.02	*ESQ-517-27 (referred to ASTM D257-99) Distance between gasket and PCB: 10mm	
	After Reflow	Ω	< 0.1		
Surface Plating Adhesion Strength			Fifth grade	*ESQ-517-16	
Hardness (Shore A)			28		
Recommend Compression			%	25	*ESQ-517-27
Restored Height after Compression Test			%	95	*ESQ-517-26 (100,000 times, 50% compression)
Stability Test	After 10 min		%	81.7	50% pressed, 80°C, 48hr
	After 1 hr		%	83.6	
	After 24 hr		%	85	
Thermal Stock Test	Thru-Thickness Resistance	After 30cycle	Ω	< 0.02	-40~+85°C 0.5hr/cycle
		After 63cycle	Ω	< 0.02	
Aging test	Thru-Thickness Resistance		Ω	0.035	*ESQ-517-20 (85°C, humidity90%, 48hr)
	Stability		%	68	
Adhesive power of soldering		Gold plated PCB	kgf	> 1	
Restricted Substances			RoHS compliant		
Salt Water Resistance			Ω	< 0.02	NaCl 5%, 35°C, 48hr
Flame Rating			UL94 V1		
Microwave Shielding Effectiveness (10MHz~1GHz)			db	Avg.78	Advantest (MIL DTL-83528C)

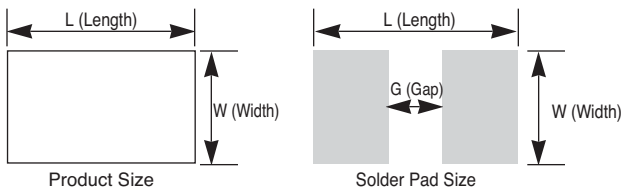
■ Soldering Break-Away Test



Break-away force is measured by pressing SMF gasket using 3mm metal plate as shown.

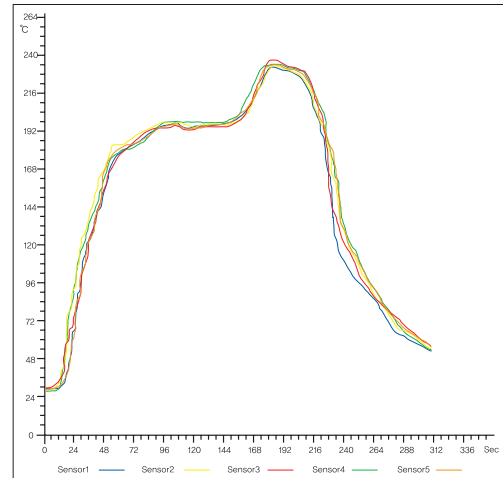


PAD DESIGN



Section	W	L	Gap size	remark
Gasket	5	8		
Pattern	5	8		
Section	5	5	2	
	5	5	1.6	

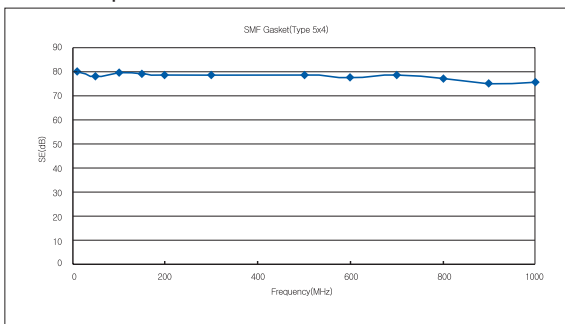
■ Reflow Condition (Gold plated PCB)



TEST DATA

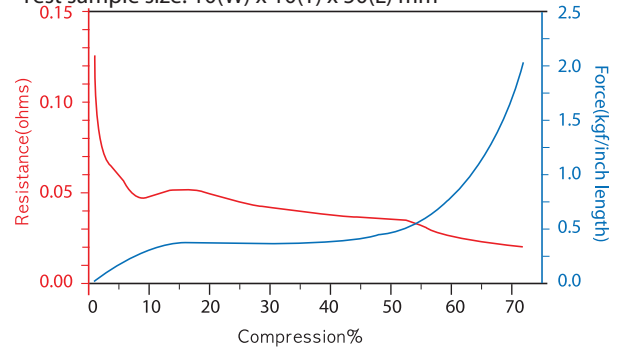
■ Shielding Effectiveness

- Test method : Advantest (MIL DTL-83528C)
- Test sample size : 5(W) x 4(T) x 8(L) mm



■ Resistance vs. Compress Test

- Test method : ESQ-517-27 (refer to various way)
- Test sample size: 10(W) x 10(T) x 50(L) mm



PACKAGING



- Packaged in a tape reel
- Quantity per reel depends on the gasket size
- Ex) 5X4X8mm are packed 2,000pcs/reel
- ※ Bulk package is also available.

USAGE EXAMPLES

High volume production such as mobile equipment, PDA, LCD/PDP

